

**AMENDMENTS TO THE SPECIFICATION**

Paragraph at page 6, lines 4-10:

~~Although~~ Although the glass component contained in the glass frit originally functions as a sintering aid for the conductive metal powder such as the silver powder or the like, in the burning process, the secondary component NiO functions to decrease the wettability of glass with the conductive metal powder to decrease the function of the glass component contained as the sintering aid in the glass frit. As a result, the particle growth of the conductive component such as silver is suppressed in the burning process to increase the resistivity of the obtained conductor film.

Paragraph at page 8, lines 24-28:

Furthermore,  $\text{MoSi}_2$  reacts with glass to form a solid solution, thereby deteriorating the fluidity of the glass and improving the wettability with the glass substrate. Therefore, the glass component of the conductive paste ~~pate~~ is segregated in the baking process at the interface between the conductor film and the glass substrate to decrease floating of the glass component to the surface of the conductor film, thereby improving solderability.